

PRODUCTION & PERFORMANCES OF ERAM* DETECTORS FOR THE T2K/ND280/HA-TPCs

* ERAM **Encaspulated Resistive** Anode Micromegas





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פכוז ויצמו לפדע WFIZMANN INSTITUTE OF SCIENCE

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The T2K / ND280 near detector upgrade

The new High-Angle TPCs readout by ERAM modules

The ERAM production:

- Diamond-Like Carbon foil Quality Control (QC) and selection
- **ERAM** "mesh-pulsing" QC
- ERAM characterization with an automated X-ray test bench

ERAM "RC maps" derived from X-ray test bench pad waveforms

Some preliminary data analysis results of the test beam of a mockup ¹/₂ HA-TPC at CERN/PS-T10 (september 2022)

Conclusions & perspectives



THE T2K EXPERIMENT THE ND280 NEAR DETETECTOR



The goal of T2K-II phase (2022-) data taking after main ring upgrade is to measure δ_{CP} at 3σ thanks to a decrease in systematic errors in ND280 from 6% to 4%.

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HA-TPC	v-TPC
Value	
$2.0\times0.8\times1.8$	0.85 x 2.2 x 1.8
90	
0.2	
275	
95 - 3 - 2	
7.8	
265	
1000	
340x420	340x360
10×11	7x10
36864	124272
800	
100	
25	
511	
0.9	1.4



CARBON RESISTIVE LAYER



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Electronics





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D. Attic doi:10.1	é et al. NIM A984, (2020), 163286. <u>1016/j.nima.2019.163286</u> 2018	D. Attié et al. NIM A1025, (2022), 1661109. doi:10.1016/j.nima.2019.166109 2019	Nov. 12 PRR 2020	Pre-series To series production 2021
CERN/T9 test beam DESY test beam ^{ERAM-01} @ DESY 2021 ^M TPC @ CERN/T10 sept 2022				
	2018 MM0-DLC#	2019 MM1-DLC1 & 2	2020 ERAM-P1 & P2	Production ERAM-xx (ERAM-01-28)
Readout PCB	Original T2K-TPC	HA-TPC V1 + ARC FEE	HA-TPC V2 + final FEE V1	HA-TPC V2 + final FEE V2
Size	34 × 36 cm ²	34 × 42 cm ²	34 × 42 cm ²	34 × 42 cm ²
Pads	48 × 36 cm ²	32 × 36 cm ²	32 × 36 cm ²	32 × 36 cm ²
Pad size	6,85 × 9,65 mm ²	10,09 × 11,18 mm ²	10,09 × 11,18 mm ²	10,09 × 11,18 mm ²
Number of pads	1728	1152	1152	1152
DLC resistivity (MΩ/sq.)	~2,5 (original foil) Not meas.on detector	0,32-0,44 (batch#P1 foils) 0,2-0,27 (meas. on detector)	0,28-0,40 (batch#P1 foils) 0,15-0,22 (meas. on detector)	~1 (foils) / ~0.28-0,4 (det.) Top TPC: 1-1.5 (foils) After baking : ~0,4-0,55
RC _{design} [ns/mm ²] RC _{data} [ns/mm ²]	~400	60 <rc<80 X-ray scan to process</rc<80 	24 <rc<35< td=""><td>55<rc<78 102<rc<145 (this="" talk)<="" td=""></rc<145></rc<78 </td></rc<35<>	55 <rc<78 102<rc<145 (this="" talk)<="" td=""></rc<145></rc<78
Insulation layer	200 μm glue + 50 μm APICAL	75 μm glue + 50 μm APICAL	200 μm glue + 50 μm APICAL	150 μm glue + 50 μm APICAL
σ (mm) For 200 ns peaking t For 412 ns peaking t	~1,6 ~2,3	~3,8 ~5,4	~5,8 ~8,3	~3,9 ~ 5,6
dE/dX (measured 1 det.) Extrapol. to 2 detectors	9 to 9.5% (e- & p) <7%	9 to 9.5 % (e-) with 0.2T <7%	Energy resolution @5.9 keV ~20% FWHM	8.5 to 10 % (e-) with 0.2T <7%
Spatial resolution (µm) Beam (Horizontal tracks) cosmics	300 (OT)	MM1-DLC1 200 (0 or 0.2T, 200/400 ns t _p) 700 (MM1-DLC2, @370V)	300-350 (ERAM-Px @370V)	@ DESY 07/ 21 200-800 μm (ERAM-01) / horizontal – 45° tracks (412ns)
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Cea ERAM PRODUCTION QA/QC



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PCB Electrical Q/C Automated test bench No defects

+ optical inspection Mechanical metrology 2,4 + - 0,1 mm

Resistivity in 4 measurement zones 360 +/-80 k Ω on final detector

All pads grounded, I < 20 nA

Detector metrology Stack thickness : PCB cut in 2 zones Glue thickness : $150 + - 5 \mu m$ Detector : 340 x 420 mm +0/-0,2 mm Detector bending < 2 mm

Cartography of defects Pedestal runs < 4 dead channels (<2 side by side)

Total thickness Mechanical metrology (with 1 mm cover) 17.6 +/- 0.05 mm Gas tightness Q/C

Final Calibration Data pad per pad and global calibration Gain, pad response, cross-talk 55Fe spectrum, spatial resolution



Cea HA-TPC PRODUCTION AND QA/QC @ CERN

NP07 HA-TPC working area at bdg. 182



HA-TPC ERAM QA/QC working area



First ¹/₂ TPC field cage

Full scale ¹/₂ TPC mock-up (8 FEE+mechanics)





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QC2 : ELECTRONIC MESH PULSING DETECTING DEFECTS BEFORE GLUING STIFFENER EXAMPLE OF A DEFECT ON ERAM-20



- ✓ The "mesh-pulsing" is a QC used before & after gluing of the mechanical stiffener to detect major defects
- A 1kHz, 300 mV square signal is pulsing the ERAM mesh \checkmark through a 50 Ω adapted cable
- The readout electronics DAQ is triggered with a NIM signal synchronized with the mesh pulsing (~5 mn run).

Amplitude mean Amplitude mean Pedestal (stddev) ADC Y-axis -axis (FEE side) - 160(sixe 20 -X-axis 20 25 after 250 equalization X-axis X-axis Amplitude mean Amplitude mean Pedestal (mean) ADC 252 ₁₇₅ Y-axis 250 100 1620 1650 1680 1710 1740 1770 1800 1830 1860 1890 1360 1440 1520 1600 1680 1760 1840 1920 X-axis

QC2: mesh pulsing before & after « repair »

QC3: X-ray scan gain

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QC3: ⁵⁵FE X-RAY SCAN **ERAM FINAL QUALIFICATION/CALIBRATION**

- ✓ Each ERAM is paired with 2 Front-End cards and "calibrated" for the use in the experiment
- Effective gain (ERAM * FE) and energy resolution @ 5.9 keV measurement on each pad with ERAM DLC layer at 350 V (nominal HV)
- \checkmark The 280 MBq ⁵⁵Fe X-ray source is collimated in a Φ 7 mm spot in the center of each pad
- ✓ The source is moved by an X-Y robot with respect to a reference pad which is "cross-scanned" with the source to locate its center (20 points every 1 mm in X&Y)
- \checkmark Gas flow is 14l/h, the scan starts when RH<0.4% and stable, full scan duration 64h (3 mn/pad) Monitoring of "environmental conditions" : Gas composition (supplier certificate), T_{amb}, P_{atm}, $\Delta p_{chamber}$, T_{gas}, Relative Humidity RH_{Gas out}
- \checkmark HV scan (330 360 V) on pad x20/Y17 (gain tuning)
- Remote shifting with local hardware support



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Gain correlation with T/P

Cea QC3: 55FE X-RAY SCAN OF ERAM-30

Tester name: Sara, ERAM ID: ERAM30, Date: 2022-07-22 08:47:59 Source: Fe55, Comments: full scan with coordinates from cross-scan 412ns shaping time and 180s run time Ampl peak thr: 50, Ampl. calc with neighbours: True Scanned: 1152/1152, total time: 65.29 h



New PCB design V1.3 from ERAM-23 \rightarrow no more non-uniformities at stiffener ribs location (see next slides)

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Histogram of gain values

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GAIN MAPS OF THE 8 ERAMs used on the ¹/₂ mockup TPC @ CERN/T10 Ref: S. Joshi (Irfu/PhD)



350

DLC voltage Production & performances of T2K/ND280/HA-TPC ERAM detectors, MPGD 2022 conterence, december 11th – 16th 2022 alain.delbart@cea.fr







FEE calibration

RC MAP DERIVED FROM X-RAY SCANS



RC is derived from the fit of the pad signal waveforms datas (leading and neighbours) with the complete modelization of the detector response

Still to understand : this RC is ~2 times higher than the RC_{design}



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ERAM-02



ERAM-12



Gain _{mean}	
1944	RC is quite well correlated to the measured
1736	
1987	
1898	
1697	DI C resistivity
1635	
1629	
1705	
1277	~1/2 RC as expected
1393	
1318	~ RC as expected
1161	



MOCKUP 1/2 HA-TPC TEST BEAM 2022 CERN/PS/T10





- Full system setup of a full size ½ HA-TPC field cage (FC) equipped with 8 ERAMs readout by their paired water cooled electronics cards within final DAQ & slow-control frameworks \checkmark
- The ¹/₂ mockup FC has the same dimensions & endcaps design as the final ¹/₂ HA-TPC except : \checkmark
 - \checkmark Thick G10 walls Vs 4 cm thick / ~2% radiation length composite walls
 - ✓ 1 cm pitch etched copper strips Vs 2.5 mm pitch strips (mirror design / 3 mm strips / 5 mm pitch)
- + The 1m drift prototype FC used at DESY 2021 is equipped with ERAM-18 (1/2 nominal RC)
- Trigger with 4 scintillators & a Cherenkov detector to select 0.5 1.5 GeV/c e+, μ +, Π +, p
- 8 full days runs with horizontal tracks with combinations of 5 drift Z distances, 3 Y positions, \checkmark 3 ERAM DLC HV, 200&412 ns peaking times, with selected e+, μ +, Π +, p at 4 different momentas





dE/dx (Y=10) for e+, μ +, π +, p @ 0.5 – 1.5 GeV/c











ERAM-23





Particle ID is well following the simulations

Spatial resolution Vs drift distance for horizontal 0.5 GeV e+ tracks (Y=20)



Spatial resolution @ 415 mm drift is 285-290 μ m for all modules, ... including ERAM-18

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CONCLUSION & PERSPECTIVES

After 3 years of development, the ERAM response modelization is now sufficiently consolidated by the the good agreement with the tests of prototypes and series detectors with different design parameters. This was particularly necessary to cope with the difficulties to control the mean resistivity and the uniformity of the DLC layer.

The RC time constant of the ERAM was fixed to ensure the spatial and energy resolutions required for the High-angle TPCs and a safe & reliable operation in the experiment (~400 k Ω /sq. and ~1500 gain).

The ERAM technology is complex and delicate to produce as are all the resistive MPGDs. The expertise and excellent partnership with the CERN/PCB workshop enabled a high yield (~80%) of high quality production of 21 ERAMs up to now.

The installations of the bottom and top high-angle TPCs in the T2K/ND280 near detector are planned for june and october 2023 respectively. By then, 16 ERAMs are to be produced and qualified for the Top TPC and the final tuning of the software tools in the ND280 event reconstruction framework using ERAM X-ray calibration datas is to be completed.





Cea QUESTIONS ?









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